

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10544178								
<b>Filing Date:</b>	24-Apr-2006								
<b>Title of Invention:</b>	INSPECTION METHOD, MANUFACTURING METHOD OF PIECE FOR ANALYSIS, ANALYSIS METHOD, ANALYZER, MANUFACTURING METHOD OF SOI WAFER, AND SOI WAFER								
<b>First Named Inventor/Applicant Name:</b>	Akira Okubo								
<b>Filer:</b>	E. Rico Hernandez/Shylah Dobson								
<b>Attorney Docket Number:</b>	061063-0317066								
Filed as Large Entity									
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>									
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%; padding: 5px;">Description</th> <th style="width: 15%; padding: 5px;">Fee Code</th> <th style="width: 15%; padding: 5px;">Quantity</th> <th style="width: 15%; padding: 5px;">Amount</th> <th style="width: 20%; padding: 5px;">Sub-Total in USD(\$)</th> </tr> </thead> </table>					Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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<b>Basic Filing:</b>									
<b>Pages:</b>									
<b>Claims:</b>									
<b>Miscellaneous-Filing:</b>									
<b>Petition:</b>									
<b>Patent-Appeals-and-Interference:</b>									
<b>Post-Allowance-and-Post-Issuance:</b>									
<b>Extension-of-Time:</b>									

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Submission- Information Disclosure Stmt	1806	1	180	180
<b>Total in USD (\$)</b>				<b>180</b>